

Fairchild Semiconductor Product Package Material Disclosure

Package Type	PQFN-8 5x6						
Weight of Package (grams)	9.23E-02						
Component	Material	Wt in grams	Substance or Material	Wt% in component	Wt% in Finished Product	CAS #	Parts per Million
Lead Frame	Metal Alloy	3.54E-02	Copper	97.43	38.37	7440-50-8 7439-89-6 7440-66-6	383657
			Iron	2.40	37.38		373797
			Zinc	0.13	0.92		9208
					0.05		499
Encapsulation	Epoxy	4.44E-02	Silica	87.00	48.12	60676-86-0 158117-90-9 85954-11-6 26834-02-6 1309-42-8 20427-58-1	481196
			Epoxy Resin	5.00	41.86		418641
			Phenol Resin	3.00	2.41		24060
			Metal Hydroxide	5.00	1.44		14436
					2.41		24060
Plating	Solder	3.50E-04	Nickel	90.00	0.38	7440-02-0 7440-05-3 7440-57-5	3793
			Palladium	9.00	0.34		3414
			Gold	1.00	0.03		341
					0.00		38
Chip	Silicon	5.35E-03	Silicon and trace metals	99.00	5.80	7440-21-3	57982
					5.74		57402
Die Attach	Adhesive	4.06E-03	Tin	91.50	4.40	7440-31-5	44001
			Antimony	8.50	4.03		40261
					0.37		3740
Wire Bond	Gold Wire	2.71E-03	Aluminum	99.99	2.94	7429-90-5 7440-02-0	29370
			Nickel	0.01	2.94		29369
					0.00		2



Materials Disclosure Disclaimer

The information provided in this Materials Disclosure is, to our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company. Also, there may not be information included in this statement regarding the minute amounts of dopant and metal materials contained within the electrically active or passive devices contained within the finished product.